SDAS096C - JANUARY 1986 - REVISED JANUARY 1995

- Functionally Equivalent to AMD's AM29863
- Power-Up High-Impedance State
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (NT) 300-mil DIPs

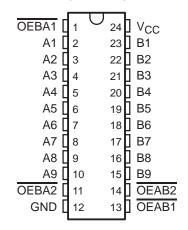
#### description

This 9-bit transceiver is designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

This device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic levels at the output-enable (OEAB1, OEAB2, OEBA1, and OEBA2) inputs.

The SN74ALS29863 is characterized for operation from 0°C to 70°C.

# DW OR NT PACKAGE (TOP VIEW)



#### **FUNCTION TABLE**

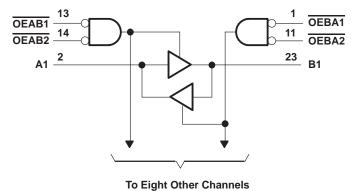
	INP	OPERATION		
OEAB1	OEAB2	OEBA1	OEBA2	OPERATION
L	L	L	L	Latch A and B
L	L	Н	Χ	A to D
L	L	Χ	Н	A to B
Н	Χ	L	L	D ( - A
Х	Н	L	L	B to A
Н	Х	Н	Χ	
Н	Χ	Χ	Н	Isolation
Х	Н	X	Н	isolation
Х	Н	Н	Χ	



## logic symbol†

#### OEBA1 EN1 11 OEBA2 13 OEAB1 EN2 14 OEAB2 23 В1 **▽ 1** ◁ 2 ▽ 22 B2 Α2 21 4 А3 В3 5 20 **B**4 Α4 19 Α5 **B5** 7 18 A6 **B6** 17 Α7 **B7** 16 **A8 B8** В9 A9

### logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V <sub>CC</sub>	 7 V
Input voltage, V <sub>I</sub> (all inputs and I/O ports)	 5.5 V
Operating free-air temperature range, TA	 0°C to 70°C
Storage temperature range	 -65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

#### recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.75	5	5.25	V
VIH	High-level input voltage	2			V
V <sub>IL</sub>	Low-level input voltage			8.0	V
ІОН	High-level output current			-24	mA
l <sub>OL</sub>	Low-level output current			48	mA
TA	Operating free-air temperature	0		70	°C

<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

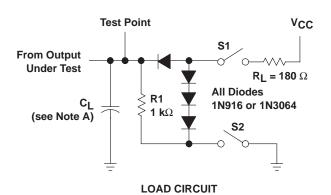
	PARAMETER	TEST CO	MIN	TYP <sup>†</sup>	MAX	UNIT		
VIK		$V_{CC} = 4.75 V$ ,	$I_{I} = -18 \text{ mA}$			-1.2	V	
Voн		\\ 475\\	$I_{OH} = -15 \text{ mA}$	2.4			.,	
		$V_{CC} = 4.75 \text{ V}$	$I_{OH} = -24 \text{ mA}$	2			<b>1</b>	
VOL		$V_{CC} = 4.75 V$ ,	$I_{OL} = 48 \text{ mA}$		0.35	0.5	V	
Ц		$V_{CC} = 5.25 V$ ,	V <sub>I</sub> = 5.5 V			0.1	mA	
	Control inputs	V 505V	.,			20		
ΊΗ	A or B ports <sup>‡</sup>	$V_{CC} = 5.25 V$ ,	V <sub>I</sub> = 2.7 V			20	μΑ	
	Control inputs	V 505V	V 0.4V			-0.1		
ΊL	A or B ports <sup>‡</sup>	$V_{CC} = 5.25 V$ ,	$V_{  } = 0.4 V$			-0.1	mA	
los§		V <sub>CC</sub> = 5.25 V,	V <sub>O</sub> = 0	-75		-250	mA	
Icc		V <sub>CC</sub> = 5.25 V	_		40	65	mA	

### switching characteristics (see Figure 1)

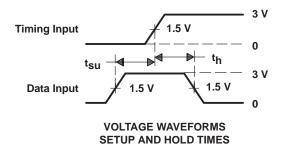
DADAMETED	FROM	то	TEGT COMPITIONS	V <sub>CC</sub> = 4.75 V to 5.25 V			
PARAMETER	(INPUT)	(OUTPUT)	TEST CONDITIONS	MIN	MAX	UNIT	
<sup>t</sup> PLH	A - :: D	D A	0 000 = 5		15		
t <sub>PHL</sub>	A or B	B or A	C <sub>L</sub> = 300 pF		15	ns	
<sup>t</sup> PLH	A D	D A	0 50 - 5		8		
t <sub>PHL</sub>	A or B	B or A	$C_L = 50 pF$		8	ns	
<sup>t</sup> PZH	OEAB or OEBA	A - : : D	0 000 = 5		20		
t <sub>PZL</sub>	OEAR OF OEBA	A or B	C <sub>L</sub> = 300 pF		23	ns	
<sup>t</sup> PZH	<u> </u>		0 50 5		15		
t <sub>PZL</sub>	OEAB or OEBA	A or B	$C_L = 50 pF$		15	ns	
<sup>t</sup> PHZ	<u> </u>	4 5	0 50 5		17		
t <sub>PLZ</sub>	OEAB or OEBA	A or B	$C_L = 50 pF$		12	ns	
<sup>t</sup> PHZ	OEAB or OEBA	A or B	C: -5 pF		9	no	
tPLZ	OEAD UI OEBA	AUIB	$C_L = 5 pF$		9	ns	

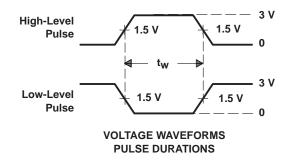
<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. ‡ For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current. § Not more than one output should be shorted at a time and duration of the short circuit should not exceed one second.

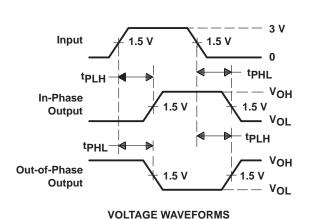
#### PARAMETER MEASUREMENT INFORMATION



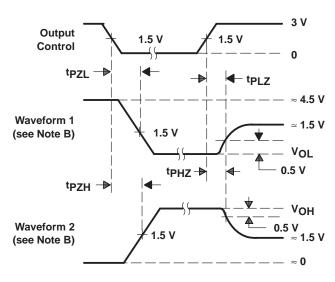
SWITCH POSITION TABLE							
TEST	S1	S2					
tPLH tPHL tPZH tPZL tPHZ tPHZ	Closed Closed Open Closed Closed Closed	Closed Closed Closed Open Closed Closed					







**PROPAGATION DELAY TIMES** 



**VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS** 

- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \,\Omega$ ,  $t_f \leq 2.5 \,$  ns.  $t_f \leq 2.5 \,$  ns.

Figure 1. Load Circuit and Voltage Waveforms



#### PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74ALS29863DW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863DWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS29863NT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS29863NTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

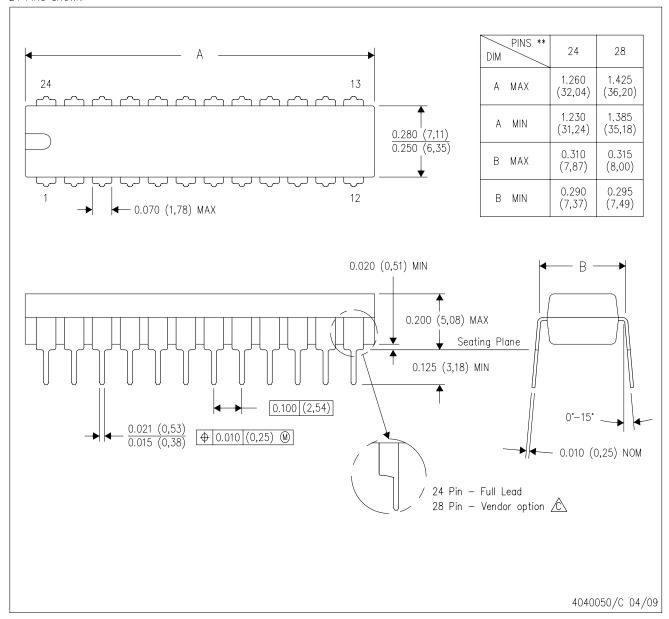
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## NT (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



## DW (R-PDSO-G24)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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